

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6823	257/678,787,788,794,798.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 10:49
L2	70	1 and (mark\$3 or indicia or label or tag or barcode or "bar code" or "machine readable" or code) with (chip or semiconductor or microchip or microprocessor or wafer) with (encapsulat\$4 or seal\$4 or epoxy or coat\$4 or cover\$3 or resin)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 11:05
L3	267	("438"/\$.ccls. "428"/\$.ccls. 1) and ((mark\$3 or indicia or label or tag or barcode or "bar code" or "machine readable" or code) and (chip or semiconductor or microchip or microprocessor or wafer)).ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 11:50
L4	8	("427"/\$.ccls.) and ((mark\$3 or indicia or label or tag or barcode or "bar code" or "machine readable" or code) and (chip or semiconductor or microchip or microprocessor or wafer)).ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 12:12
L5	1	"5801067".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 12:12
L6	2	("6288335" "4719502").pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 12:34
L7	2	("6288335" "4719502").pn. and (epoxy or resin)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 13:38
L8	1840	"216"/\$.ccls. and epoxy	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 13:38
L9	4	"216"/\$.ccls. and epoxy same (indicia or barcode or "bar code" or label or mark\$3) same (IC or "integrated circuit" or chip or semiconductor)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 13:38
L10	16	(ic or chip or "integrated circuit" or semiconductor) with (epoxy) with protect\$4 with clear\$4	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 13:58
L11	1460	(ic or chip or "integrated circuit" or semiconductor) with (epoxy) with protect\$4	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 13:59

L12	63	(ic or chip or "integrated circuit" or semiconductor) with (epoxy) with protect\$4 with (clear\$4 or transparent\$4 or read\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 14:02
L13	47	12 not 10	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 13:59
L14	6	chip with (ic or "integrated circuit" or semiconductor) with (epoxy) with protect\$4 with (clear\$4 or transparent\$4 or read\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 14:03
L15	89	chip with (ic or "integrated circuit" or semiconductor) with (epoxy) with (clear\$4 or transparent\$4 or read\$4)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 14:15
L16	26	chip with (ic or "integrated circuit" or semiconductor) with (epoxy) with (glob)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 14:20
L17	3598	protect\$3 with coat\$4 with epoxy	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 14:21
L18	1567	protect\$3 near5 coat\$4 near5 epoxy	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 14:21
L19	32	17 with (semiconductor or ic or "integrated circuit") near3 chip	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 14:23
L20	2	17 with (semiconductor or ic or "integrated circuit") same (indicia or "bar code" or barcode or mark\$3 or "machine readable")	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 14:23
L21	368	(semiconductor or ic or "integrated circuit") same (indicia or "bar code" or barcode or mark\$3 or "machine readable") same epoxy	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 14:27
L22	176	(semiconductor or ic or "integrated circuit") near5 (component or chip or device) same (indicia or "bar code" or barcode or mark\$3 or "machine readable") same epoxy	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 14:28
L23	14	("4794238" "4812631" "4962432" "4972068" "4981351" "4987434" "5083814" "5122645" "5164574" "5164865" "5212367" "5218192" "5376957" "5547501").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/23 14:40
L24	16	("5801067").URPN.	USPAT	OR	ON	2005/03/23 14:41

L27	2	("6288335" "4719502").pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 16:01
L28	245	("257"/\$.ccls. "438"/\$.ccls. "428"/\$.ccls. "427"/\$.ccls. "235"/\$.ccls.) and (mark\$3 or indicia or barcode or "bar code" or "machine readable") same (layer or coat\$3 or encapsula\$4) same (resin or epoxy) same (chip or device) same (semiconductor or ic or "integrated circuit" or electronic)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 16:04
L29	158	("257"/\$.ccls. "438"/\$.ccls. "428"/\$.ccls. "427"/\$.ccls. "235"/\$.ccls.) and (mark or marking or indicia or barcode or "bar code" or "machine readable") same (layer or coat\$3 or encapsula\$4) with (resin or epoxy) same (chip or device or package or housing) with (semiconductor or ic or "integrated circuit" or electronic)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 16:04
L30	162	("257"/\$.ccls. "438"/\$.ccls. "428"/\$.ccls. "427"/\$.ccls. "235"/\$.ccls.) and (mark or marking or indicia or barcode or "bar code" or "machine readable") same (layer or coat\$3 or encapsula\$4) with (resin or epoxy) same (chip or device or package or housing) with (semiconductor or ic or "integrated circuit" or electronic or circuit)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 16:06
L31	5	("5166772" "5317195" "5557142" "6086979" "6261919").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/23 16:09
L32	5	31 and (resin or epoxy or encapsula\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/23 16:09
L33	0	("6448632").URPN.	USPAT	OR	ON	2005/03/23 16:10
L34	1	("4939316").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/23 16:16
L35	10	("5644102").URPN.	USPAT	OR	ON	2005/03/23 16:16
L36	1	"6337122".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 17:34

L37	74	"257"/\$.ccls. and resin with mask with package	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 17:46
L38	48	37 and epoxy	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 17:37
L39	782	"257"/\$.ccls. and epoxy with resin with (transparent or clear or translucent)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 17:47
L40	56	"257"/\$.ccls. and epoxy with resin with (transparent or clear or translucent) with encapsul\$4	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 17:48
L41	33	(US-20050051909-\$ or US-20050009298-\$ or US-20040265596-\$ or US-20040256463-\$ or US-20030161112-\$ or US-20030126741-\$ or US-20010042901-\$ or US-20030072926-\$ or US-20030077418-\$).did. or (US-6796024-\$ or US-6680220-\$ or US-6559536-\$ or US-6448632-\$ or US-4537059-\$ or US-4125418-\$ or US-6703105-\$ or US-6489007-\$ or US-6420790-\$ or US-6143587-\$ or US-5801067-\$ or US-6717256-\$ or US-6352880-\$ or US-6400032-\$ or US-6817538-\$ or US-5644102-\$ or US-6139978-\$ or US-4167647-\$).did. or (JP-2002175956-\$ or JP-02246247-\$ or JP-01238046-\$ or JP-63263748-\$ or JP-05166949-\$ or JP-62169448-\$).did.	US-PGPUB; USPAT; JPO	OR	ON	2005/03/23 17:51
L42	10	41 and "epoxy resin"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 17:54
L43	227	"257"/\$.ccls. and "epoxy resin" with (coat\$4) with chip	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 17:55
L44	8	"257"/\$.ccls. and "epoxy resin" with (coat\$4) with chip with (clear or transparent)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 17:55
L45	385	"257"/\$.ccls. and (transparent or clear) near3 "epoxy resin"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 18:01
L46	237	"257"/\$.ccls. and (transparent or clear) adj "epoxy resin"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 18:22

L47	17	"257"/\$.ccls. and color with (encapsulat\$4) with (chip or package)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 18:28
L48	1	JP02002175956A	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 19:28
S1	1999	(mark\$3 or indicia or label or tag or barcode or "bar code" or "machine readable" or code) with (chip or semiconductor or microchip or microprocessor) with (encapsulat\$4 or seal\$4 or epoxy or coat\$4 or cover\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/22 17:28
S2	182	(mark\$3 or indicia or label or tag or barcode or "bar code" or "machine readable" or code) with (chip or semiconductor or microchip or microprocessor) with (encapsulat\$4 or seal\$4 or epoxy or coat\$4 or cover\$3 or resin) same (Identification or Identify\$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/22 16:44
S3	5	("5166772" "5317195" "5557142" "6086979" "6261919").pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/22 17:27
S4	706	("257"/\$.ccls. "347"/\$.ccls. "438"/\$.ccls.) and S1	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/22 17:29
S5	2227	(mark\$3 or indicia or label or tag or barcode or "bar code" or "machine readable" or code) with (chip or semiconductor or microchip or microprocessor) with (encapsulat\$4 or seal\$4 or epoxy or coat\$4 or cover\$3 or resin)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 10:49
S6	801	("257"/\$.ccls. "347"/\$.ccls. "438"/\$.ccls.) and S5	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/03/23 10:49

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L1	4707	427/7,96,258,595,162,307,309.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/23 19:31
L2	17225	"216"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/23 19:31
L3	231	"216"/\$.ccls. and (chip or device or circuit) with encapsula\$4	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/23 19:31
L4	28	1 and (chip or device or circuit) with encapsula\$4	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/23 19:31